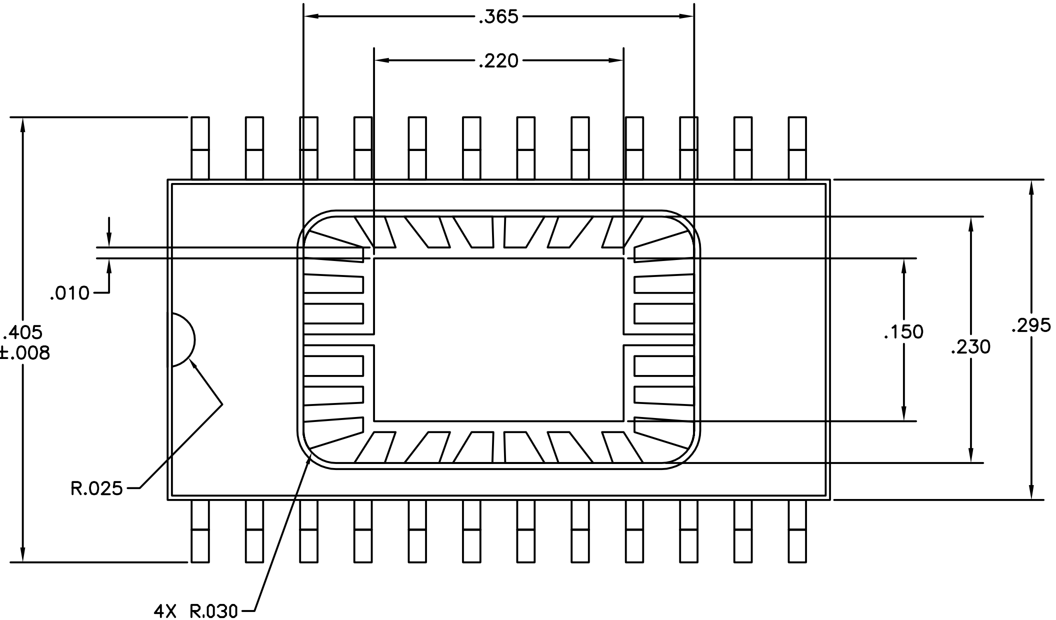
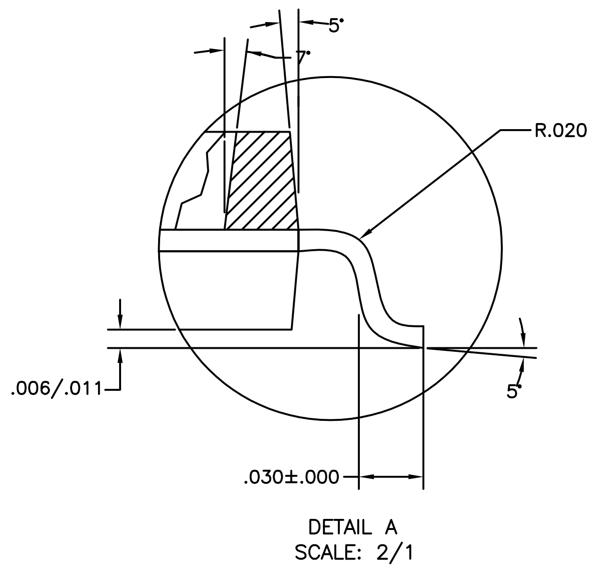
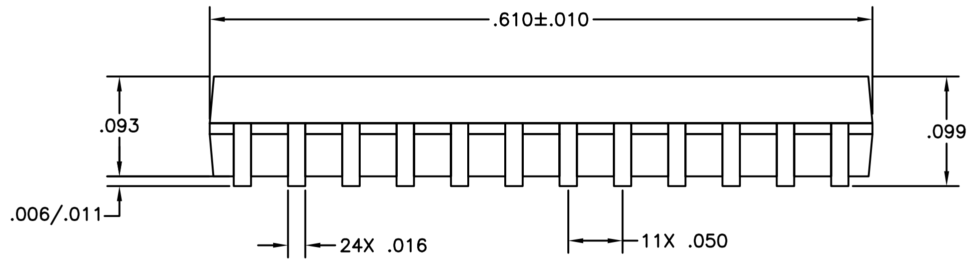
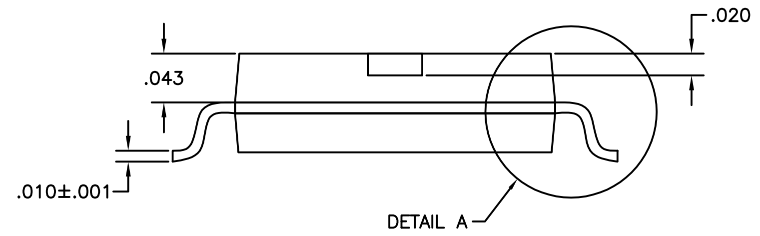
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10792	11/01/06	PRODUCTION RELEASE	D.MORRIS



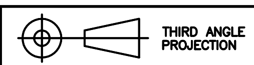






NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEADFRAME: COPPER, FH 194.
3. LEAD FINISH: FULL Au PLATE.
4. DIE PAD: .220" x .150".



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
X.XX ± 0.01   X.XXXX ±---
X.XXX ± 0.005   ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	11/01/06
APP BY	P. FLASKERUD	DATE	11/01/06
CUSTOMER	---		

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SEMPAC, INC.
Open-Pak™ Technologies
www.sempac.com
568 E. WEDDELL DRIVE, SUITE 5
SUNNYVALE, CALIFORNIA 94089
PHONE: (408) 400-9002   FAX: (408) 400-9006

24 Lead 300 mils SOIC Open-Pak

SIZE	PART NO.	REV
A	SOIC300-24-OP-01	4

SCALE NONE | CAD FILE SOIC300-24-OP-01-R4.DWG | SHEET 1 OF 1

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REV 1 ECN 10598